National Taiwan Normal University International Degree-Seeking Student Semiconductor Credit Program Scholarship Implementation Guidelines

Approved on February 2, 2026

1. Purpose

These Guidelines have been formulated to provide a scholarship with the express purpose of encouraging NTNU international degree-seeking students to enroll in the University's Semiconductor Credit Program, as well as enhance their Chinese language proficiency during their studies in Taiwan.

2. Applicant Eligibility

Applicants shall meet the following conditions:

1. Applicants shall be international students or overseas Chinese students enrolled in Bachelor's or Master's degree programs at NTNU, including those in dual-degree Bachelor's or Master's programs at NTNU.
2. No specific major is required; however, students majoring in semiconductor or science and engineering-related fields will be given priority.
3. Eligibility is limited to students who have not previously received this scholarship.

3. Applicants Shall Meet the Following Grade Requirements:

1. At the time of application, the student's average grade for their most recent semester shall be 70 (out of 100) or higher, or the equivalent of a 2.44 GPA.
2. At the time of application, the student's conduct grade for their most recent semester shall be 87 (out of 100) or higher, or the equivalent of a 3.88 GPA.

4. Coursework and Proficiency Requirements

Students shall complete the following requirements during their time of study:

1. *Semiconductor Credit Program:* Students shall complete 21 academic credits in semiconductor-related courses offered by NTNU, primarily from those specified in the university's current Semiconductor Credit Program. Courses may be taught in either Chinese or English. Of the 21 credits, students must complete at least one course related to semiconductor manufacturing processes (e.g., *Semiconductor Materials and Processing, Semiconductor Fabrication Process, Silicon VLSI Technology- Fundamentals, Practice and Modeling and Introduction to Semiconductor Processing).*

2. *Course Completion Report:* As supporting evidence of their learning outcomes, students shall submit one (1) final report or project report from a semiconductor manufacturing process–related course taken as part of the Semiconductor Credit Program.
3. *Chinese Language Proficiency:* Students shall obtain a Ministry of Education issued Test of Chinese as a Foreign Language (TOCFL) Listening and Reading Certificate of Level 4 (or CEFR B2) or above. The certificate shall be valid within two years of the application date.
4. *Internship Plan*: Students shall apply for the TSMC DNA Internship Program during their time of study and provide proof of application.
5. *Completion Deadline*: Applicants shall complete the above requirements within their prescribed period of study at NTNU, and shall submit their applications no later than one (1) semester before their scheduled graduation; those who fail to complete the requirements by this deadline shall not be eligible to either apply for or receive this scholarship thereafter.

5. Application Period

The application period shall be held annually in March or October, subject to the official announcement for the respective year.

6. Required Application Materials

1. Application Form (must be signed by the applicant).
2. Official transcript of academic study.
3. Student Rewards, Punishments, and Conduct Score Conversion Certificate.
4. One (1) letter of recommendation from a faculty member of the applicant's department or graduate institute. The recommendation letter must follow the prescribed format and be submitted in a sealed envelope.
5. Course completion report for a semiconductor-related course (to be submitted when applying for the first phase of the scholarship).
6. A photocopy of the applicant's TOCFL B2 Listening and Reading Certificate (to be submitted when applying for the second phase of the scholarship).

7. Application Review Process

Applications will be evaluated by a committee composed of at least five (5) members from the Office of International Affairs (OIA). Following a review of all submitted documents, the results of the committee's decisions shall be sent to the OIA's Vice-President for International Affairs for approval. Even if applicants meet all scholarship eligibility requirements, the awarding of scholarships shall be subject to the final decision of the committee and the approval of the University.

8. Scholarship Disbursement Procedures

The maximum scholarship amount for each recipient shall be NT$90,000, which will be disbursed in two phases:

1. First Phase: NT$70,000

   The first phase of the scholarship shall be disbursed upon the student's completion of the Semiconductor Credit Program; their receipt of a corresponding certificate of completion; and the submission of one (1) course completion report.
2. Second Phase: NT$20,000

   The second phase of the scholarship shall be disbursed upon the student's submission of a TOCFL B2 (or higher) Listening and Reading Certificate; and proof of application to the TSMC DNA Internship Program.

9. Other Regulations

1. In cases where an applicant provides false information, submits forged documents, or obtains the scholarship through other improper means, the disbursed funds shall be recovered and the applicant's eligibility for future applications shall be revoked.
2. This scholarship may not be received concurrently with other scholarships or grants of a similar nature. In the event of overlap, the recipient shall proactively report it and return any funds received in accordance with the relevant regulations.
3. If the disbursement of this scholarship is subject to the relevant tax regulations of the Republic of China (Taiwan), the recipient (including international students) shall comply with the current *Income Tax Act* and related regulations of the Republic of China (Taiwan) and shall bear responsibility for paying any applicable taxes.
4. The University may, in accordance with actual needs, revise or supplement these provisions at any time.

10. Funding for this scholarship shall be provided through industry–academia collaboration subsidies and may be adjusted depending on the actual funding situation. The University reserves the right to adjust the content of these Guidelines and the number of scholarship recipients. Any matters not covered herein shall be handled in accordance with the relevant regulations.

11. These Guidelines, and any ensuing revisions, shall be implemented following their submission by the Office of International Affairs for approval by the University President.